

L Number	Hits	Search Text	DB	Time stamp
10	3639	mirror\$2 with wafer	USPAT	2002/11/17 18:50
11	973	(mirror\$2 with wafer) and photoresist	USPAT	2002/11/17 18:52
12	342	((mirror\$2 with wafer) and photoresist) and (cut\$3 or singulat\$3 or slice or dice or saw)	USPAT	2002/11/17 18:54
13	177	((mirror\$2 with wafer) and photoresist) and (cut\$3 or singulat\$3 or slice or dice or saw)) and (chip or die)	USPAT	2002/11/17 19:33
14	0	6407844.URPN.	USPAT	2002/11/17 19:03
15	0	6407844.URPN.	USPAT	2002/11/17 19:04
16	11	("4942766" "5488862" "5548618" "5629790" "5658710" "5841553" "5861549" "5969465" "6064779" "6123985" "6175443").PN.	USPAT	2002/11/17 19:04
17	3	5668062.URPN.	USPAT	2002/11/17 19:24
18	15	("3537169" "3677875" "4455739" "4542397" "5061049" "5079544" "5105369" "5182233" "5278652" "5341024" "5393706" "5435876" "5501104" "5527744" "5534102").PN.	USPAT	2002/11/17 19:24
23	71	-(chip or die) near mirror\$2) and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/17 19:41
24	51	438/460.ccls. and mirror	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/17 19:42
25	58	438/460.ccls. and mirror\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/17 19:59
26	2	6335224.URPN.	USPAT	2002/11/17 19:50
27	115	(dmd) and (chip or dier) and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/17 20:00
28	136	(dmd) and (chip or die) and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/17 20:00